

74HC3G07; 74HCT3G07

Triple buffer with open-drain outputs

Rev. 4 — 16 December 2013

Product data sheet

1. General description

The 74HC3G07; 74HCT3G07 is a triple buffer with open-drain outputs. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of V_{CC} .

2. Features and benefits

- Wide supply voltage range from 2.0 V to 6.0 V
- Input levels:
 - ◆ For 74HC3G07: CMOS level
 - ◆ For 74HCT3G07: TTL level
- Complies with JEDEC standard no. 7 A
- High noise immunity
- Low power dissipation
- Balanced propagation delays
- ESD protection:
 - ◆ HBM JESD22-A114E exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V
- Multiple package options
- Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ and $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$

3. Ordering information

Table 1. Ordering information

| Type number | Package | | | |
|---------------------------|---|--------|--|----------|
| | Temperature range | Name | Description | Version |
| 74HC3G07DP 74HCT3G07DP | $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$ | TSSOP8 | plastic thin shrink small outline package; 8 leads; body width 3 mm; lead length 0.5 mm | SOT505-2 |
| 74HC3G07DC 74HCT3G07DC | $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$ | VSSOP8 | plastic very thin shrink small outline package; 8 leads; body width 2.3 mm | SOT765-1 |
| 74HC3G07GD 74HCT3G07GD | $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$ | XSON8 | plastic extremely thin small outline package; no leads; 8 terminals; body $3 \times 2 \times 0.5$ mm | SOT996-2 |



4. Marking

Table 2. Marking code

| Type number | Marking code ^[1] |
|-------------|-----------------------------|
| 74HC3G07DP | H07 |
| 74HCT3G07DP | T07 |
| 74HC3G07DC | H07 |
| 74HCT3G07DC | T07 |
| 74HC3G07GD | H07 |
| 74HCT3G07GD | T07 |

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

5. Functional diagram

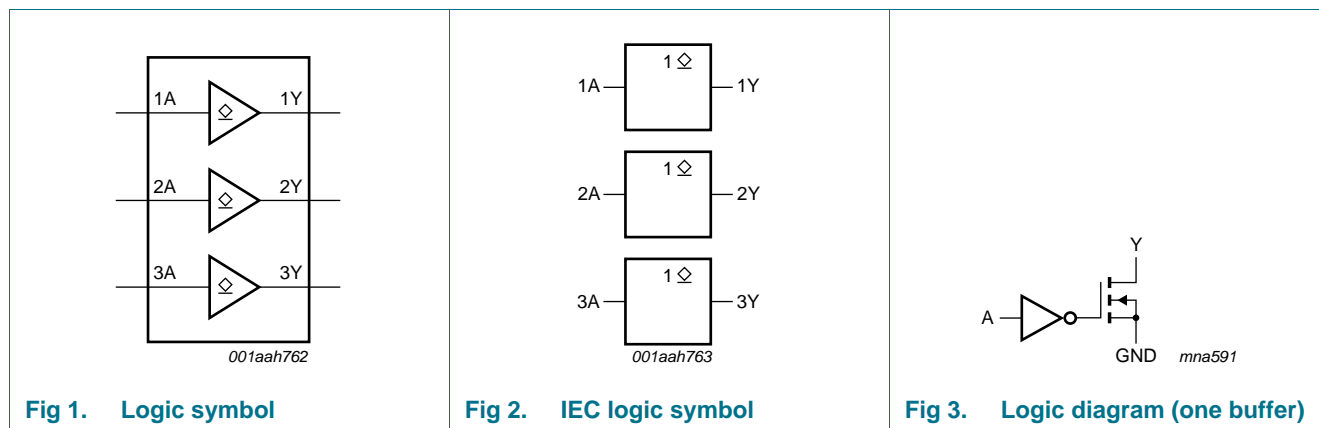


Fig 1. Logic symbol

Fig 2. IEC logic symbol

Fig 3. Logic diagram (one buffer)

6. Pinning information

6.1 Pinning

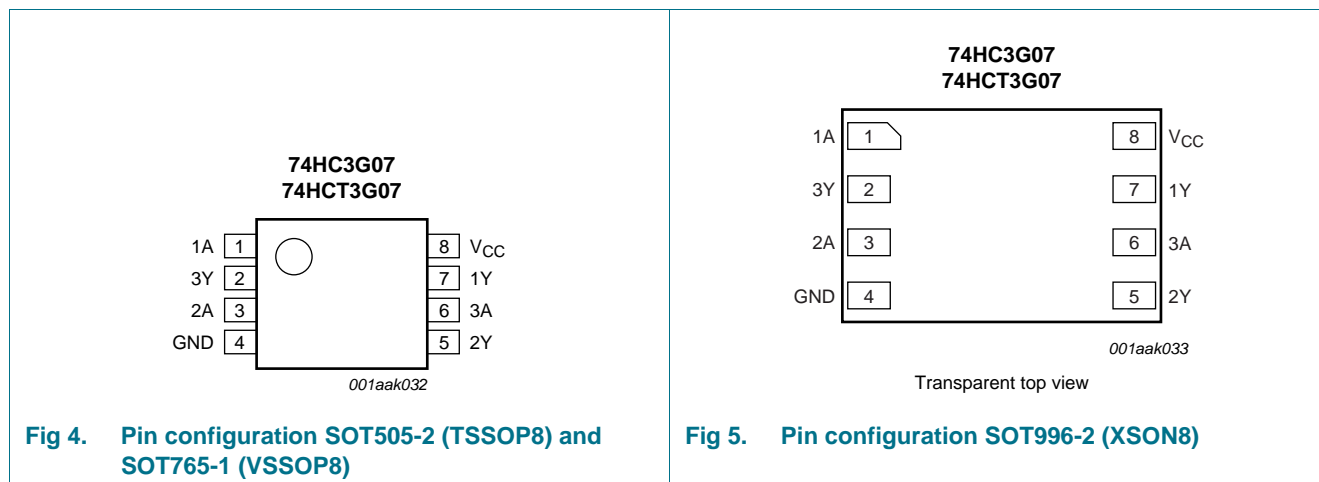


Fig 4. Pin configuration SOT505-2 (TSSOP8) and SOT765-1 (VSSOP8)

Fig 5. Pin configuration SOT996-2 (XSON8)

6.2 Pin description

Table 3. Pin description

| Symbol | Pin | Description |
|-----------------|---------|----------------|
| 1A, 2A, 3A | 1, 3, 6 | data input |
| GND | 4 | ground (0 V) |
| 1Y, 2Y, 3Y | 7, 5, 2 | data output |
| V _{CC} | 8 | supply voltage |

7. Functional description

Table 4. Function table^[1]

| Input nA | Output nY |
|----------|-----------|
| L | L |
| H | Z |

[1] H = HIGH voltage level; L = LOW voltage level; Z = high-impedance OFF-state.

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|------------------|---------------------------|---|----------|-----------------------|------|
| V _{CC} | supply voltage | | -0.5 | 7.0 | V |
| I _{IK} | input clamping current | V _I < -0.5 V or V _I > V _{CC} + 0.5 V | [1] - | ±20 | mA |
| I _{OK} | output clamping current | V _O < -0.5 V | [1] -20 | - | mA |
| V _O | output voltage | active mode | [1] -0.5 | V _{CC} + 0.5 | V |
| | | high-impedance mode | [1] -0.5 | 7.0 | V |
| I _O | output current | V _O = -0.5 V to 7.0 V | [1] -25 | - | mA |
| I _{CC} | supply current | | [1] - | 50 | mA |
| I _{GND} | ground current | | [1] -50 | - | mA |
| T _{stg} | storage temperature | | -65 | +150 | °C |
| P _D | dynamic power dissipation | T _{amb} = -40 °C to +125 °C | [2] - | 300 | mW |

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For TSSOP8 package: above 55 °C the value of P_{tot} derates linearly with 2.5 mW/K.
 For VSSOP8 package: above 110 °C the value of P_{tot} derates linearly with 8 mW/K.
 For XSON8 package: above 118 °C the value of P_{tot} derates linearly with 7.8 mW/K.

9. Recommended operating conditions

Table 6. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | 74HC3G07 | | | 74HCT3G07 | | | Unit |
|------------------|-------------------------------------|-------------------------|----------|------|-----------------|-----------|------|-----------------|------|
| | | | Min | Typ | Max | Min | Typ | Max | |
| V _{CC} | supply voltage | | 2.0 | 5.0 | 6.0 | 4.5 | 5.0 | 5.5 | V |
| V _I | input voltage | | 0 | - | 6.0 | 0 | - | 5.5 | V |
| V _O | output voltage | | 0 | - | V _{CC} | 0 | - | V _{CC} | V |
| T _{amb} | ambient temperature | | -40 | +25 | +125 | -40 | +25 | +125 | °C |
| Δt/ΔV | input transition rise and fall rate | V _{CC} = 2.0 V | - | - | 625 | - | - | - | ns/V |
| | | V _{CC} = 4.5 V | - | 1.67 | 139 | - | 1.67 | 139 | ns/V |
| | | V _{CC} = 6.0 V | - | - | 83 | - | - | - | ns/V |

10. Static characteristics

Table 7. Static characteristics

Voltages are referenced to GND (ground = 0 V). All typical values are measured at T_{amb} = 25 °C.

| Symbol | Parameter | Conditions | -40 °C to +85 °C | | | -40 °C to +125 °C | | Unit |
|-----------------|--------------------------|--|------------------|--------------------|------|-------------------|------|------|
| | | | Min | Typ ^[1] | Max | Min | Max | |
| 74HC3G07 | | | | | | | | |
| V _{IH} | HIGH-level input voltage | V _{CC} = 2.0 V | 1.5 | 1.2 | - | 1.5 | - | V |
| | | V _{CC} = 4.5 V | 3.15 | 2.4 | - | 3.15 | - | V |
| | | V _{CC} = 6.0 V | 4.2 | 3.2 | - | 4.2 | - | V |
| V _{IL} | LOW-level input voltage | V _{CC} = 2.0 V | - | 0.8 | 0.5 | - | 0.5 | V |
| | | V _{CC} = 4.5 V | - | 2.1 | 1.35 | - | 1.35 | V |
| | | V _{CC} = 6.0 V | - | 2.8 | 1.8 | - | 1.8 | V |
| V _{OL} | LOW-level output voltage | V _I = V _{IH} or V _{IL} | | | | | | |
| | | I _O = 20 μA; V _{CC} = 2.0 V | - | 0 | 0.1 | - | 0.1 | V |
| | | I _O = 20 μA; V _{CC} = 4.5 V | - | 0 | 0.1 | - | 0.1 | V |
| | | I _O = 20 μA; V _{CC} = 6.0 V | - | 0 | 0.1 | - | 0.1 | V |
| | | I _O = 4.0 mA; V _{CC} = 4.5 V | - | 0.15 | 0.33 | - | 0.4 | V |
| | | I _O = 5.2 mA; V _{CC} = 6.0 V | - | 0.16 | 0.33 | - | 0.4 | V |
| I _I | input leakage current | V _I = V _{CC} or GND; V _{CC} = 6.0 V | - | - | ±0.1 | - | ±1.0 | μA |
| I _{LO} | output leakage current | V _I = V _{IH} ; V _O = V _{CC} or GND | - | - | ±5.0 | - | ±10 | μA |
| I _{CC} | supply current | per input pin; V _{CC} = 6.0 V; V _I = V _{CC} or GND; I _O = 0 A; | - | - | 10 | - | 20 | μA |
| C _I | input capacitance | | - | 1.5 | - | - | - | pF |

Table 7. Static characteristics ...continued

Voltages are referenced to GND (ground = 0 V). All typical values are measured at $T_{amb} = 25\text{ }^{\circ}\text{C}$.

| Symbol | Parameter | Conditions | -40 °C to +85 °C | | | -40 °C to +125 °C | | Unit |
|------------------|---------------------------|---|------------------|--------------------|-----------|-------------------|-----------|---------------|
| | | | Min | Typ ^[1] | Max | Min | Max | |
| 74HCT3G07 | | | | | | | | |
| V_{IH} | HIGH-level input voltage | $V_{CC} = 4.5\text{ V to }5.5\text{ V}$ | 2.0 | 1.6 | - | 2.0 | - | V |
| V_{IL} | LOW-level input voltage | $V_{CC} = 4.5\text{ V to }5.5\text{ V}$ | - | 1.2 | 0.8 | - | 0.8 | V |
| V_{OL} | LOW-level output voltage | $V_I = V_{IH}$ or V_{IL} | | | | | | |
| | | $I_O = 20\text{ }\mu\text{A}$; $V_{CC} = 4.5\text{ V}$ | - | 0 | 0.1 | - | 0.1 | V |
| | | $I_O = 4.0\text{ mA}$; $V_{CC} = 4.5\text{ V}$ | - | 0.15 | 0.33 | - | 0.4 | V |
| I_I | input leakage current | $V_I = V_{CC}$ or GND; $V_{CC} = 5.5\text{ V}$ | - | - | ± 1.0 | - | ± 1.0 | μA |
| I_{LO} | output leakage current | $V_I = V_{IH}$; $V_O = V_{CC}$ or GND | - | - | ± 5.0 | - | ± 10 | μA |
| I_{CC} | supply current | per input pin; $V_{CC} = 5.5\text{ V}$; $V_I = V_{CC}$ or GND; $I_O = 0\text{ A}$; | - | - | 10 | - | 20 | μA |
| ΔI_{CC} | additional supply current | per input; $V_{CC} = 4.5\text{ V to }5.5\text{ V}$; $V_I = V_{CC} - 2.1\text{ V}$; $I_O = 0\text{ A}$ | - | - | 375 | - | 410 | μA |
| C_I | input capacitance | | - | 1.5 | - | - | - | pF |

[1] Typical values are measured at $T_{amb} = 25\text{ }^{\circ}\text{C}$.

11. Dynamic characteristics

Table 8. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V); all typical values are measured at $T_{amb} = 25\text{ }^{\circ}\text{C}$; for test circuit see [Figure 7](#).

| Symbol | Parameter | Conditions | -40 °C to +85 °C | | | -40 °C to +125 °C | | Unit |
|-----------------|------------------------------------|--|------------------|-----|-----|-------------------|-----|------|
| | | | Min | Typ | Max | Min | Max | |
| 74HC3G07 | | | | | | | | |
| t_{PZL} | OFF-state to LOW propagation delay | nA to nY; see Figure 6 | | | | | | |
| | | $V_{CC} = 2.0\text{ V}$ | - | 25 | 95 | - | 125 | ns |
| | | $V_{CC} = 4.5\text{ V}$ | - | 9 | 19 | - | 25 | ns |
| | | $V_{CC} = 6.0\text{ V}$ | - | 7 | 16 | - | 20 | ns |
| t_{PLZ} | LOW to OFF-state propagation delay | nA to nY; see Figure 6 | | | | | | |
| | | $V_{CC} = 2.0\text{ V}$ | - | 25 | 95 | - | 125 | ns |
| | | $V_{CC} = 4.5\text{ V}$ | - | 11 | 23 | - | 30 | ns |
| | | $V_{CC} = 6.0\text{ V}$ | - | 10 | 23 | - | 26 | ns |
| t_{THL} | HIGH to LOW output transition time | nY; see Figure 6 | | | | | | |
| | | $V_{CC} = 2.0\text{ V}$ | - | 18 | 95 | - | 125 | ns |
| | | $V_{CC} = 4.5\text{ V}$ | - | 6 | 19 | - | 25 | ns |
| | | $V_{CC} = 6.0\text{ V}$ | - | 5 | 16 | - | 20 | ns |
| C_{PD} | power dissipation capacitance | $V_I = \text{GND to } V_{CC}$ | ^[1] | 4 | - | - | - | pF |

Table 8. Dynamic characteristics ...continued

Voltages are referenced to GND (ground = 0 V); all typical values are measured at $T_{amb} = 25\text{ }^{\circ}\text{C}$; for test circuit see [Figure 7](#).

| Symbol | Parameter | Conditions | -40 °C to +85 °C | | | -40 °C to +125 °C | | Unit |
|------------------|------------------------------------|---|------------------|-----|-----|-------------------|-----|------|
| | | | Min | Typ | Max | Min | Max | |
| 74HCT3G07 | | | | | | | | |
| t_{PZL} | OFF-state to LOW propagation delay | nA to nY; see Figure 6 $V_{CC} = 4.5\text{ V}$ | - | 11 | 27 | - | 32 | ns |
| t_{PLZ} | LOW to OFF-state propagation delay | nA to nY; see Figure 6 $V_{CC} = 4.5\text{ V}$ | - | 10 | 26 | - | 31 | ns |
| t_{THL} | HIGH to LOW output transition time | $V_{CC} = 4.5\text{ V}$; see Figure 6 | - | 6 | 19 | - | 22 | ns |
| C_{PD} | power dissipation capacitance | $V_I = \text{GND to } V_{CC} - 1.5\text{ V}$ [1] | - | 4 | - | - | - | pF |

[1] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f_i = input frequency in MHz;

f_o = output frequency in MHz;

C_L = output load capacitance in pF;

V_{CC} = supply voltage in V;

N = number of inputs switching;

$\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of outputs.

12. Waveforms

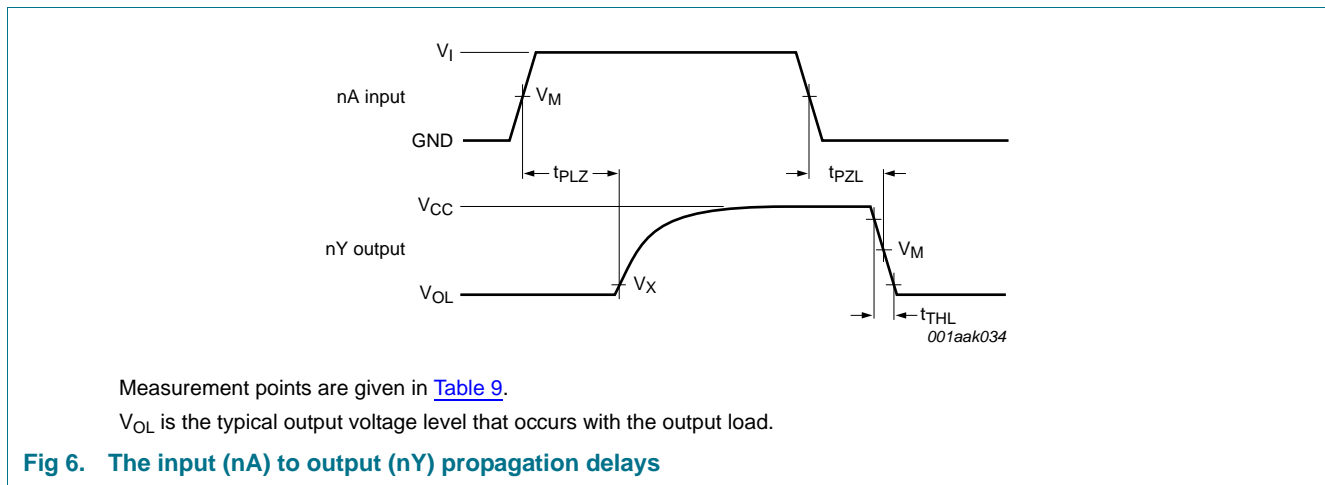
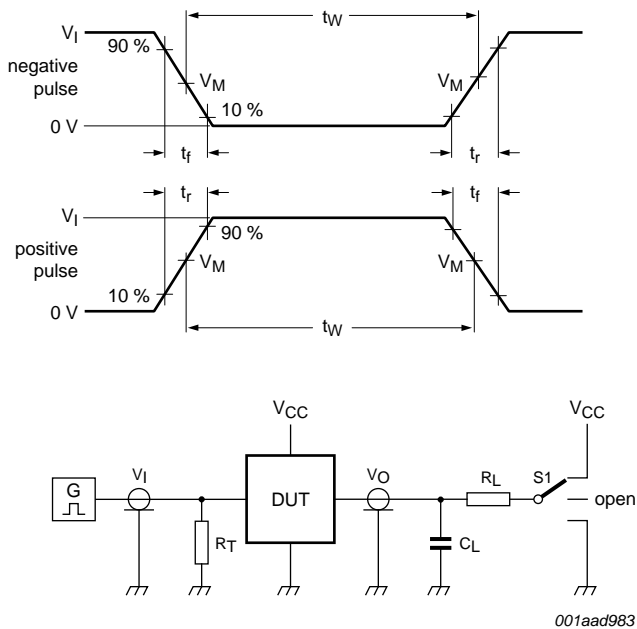


Table 9. Measurement points

| Type | Input | Output | |
|-----------|---------------------|---------------------|---------------------|
| | V_M | V_M | V_X |
| 74HC3G07 | $0.5 \times V_{CC}$ | $0.5 \times V_{CC}$ | $0.1 \times V_{CC}$ |
| 74HCT3G07 | 1.3 V | 1.3 V | $0.1 \times V_{CC}$ |



Test data is given in [Table 10](#).

Definitions for test circuit:

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

C_L = Load capacitance including jig and probe capacitance.

R_L = Load resistance.

S1 = Test selection switch.

Fig 7. Test circuit for measuring switching times

Table 10. Test data

| Type | Input | | Load | | S1 position |
|-----------|-----------------|-------------|-------|--------------|--------------------|
| | V_I | t_r, t_f | C_L | R_L | t_{PZL}, t_{PLZ} |
| 74HC3G07 | GND to V_{CC} | ≤ 6 ns | 50 pF | 1 k Ω | V_{CC} |
| 74HCT3G07 | GND to 3 V | ≤ 6 ns | 50 pF | 1 k Ω | V_{CC} |

13. Package outline

TSSOP8: plastic thin shrink small outline package; 8 leads; body width 3 mm; lead length 0.5 mm SOT505-2

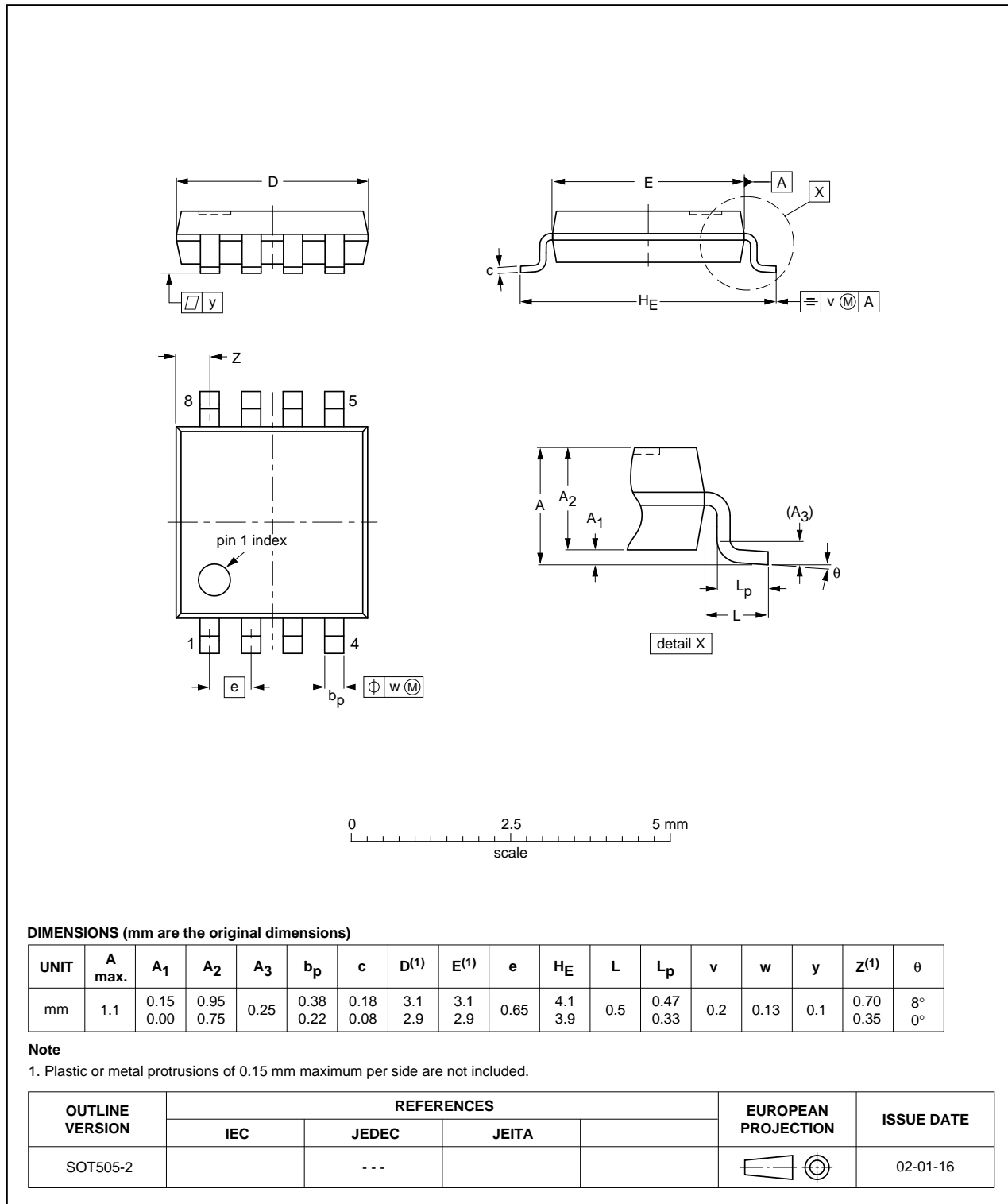


Fig 8. Package outline SOT505-2 (TSSOP8)

VSSOP8: plastic very thin shrink small outline package; 8 leads; body width 2.3 mm

SOT765-1

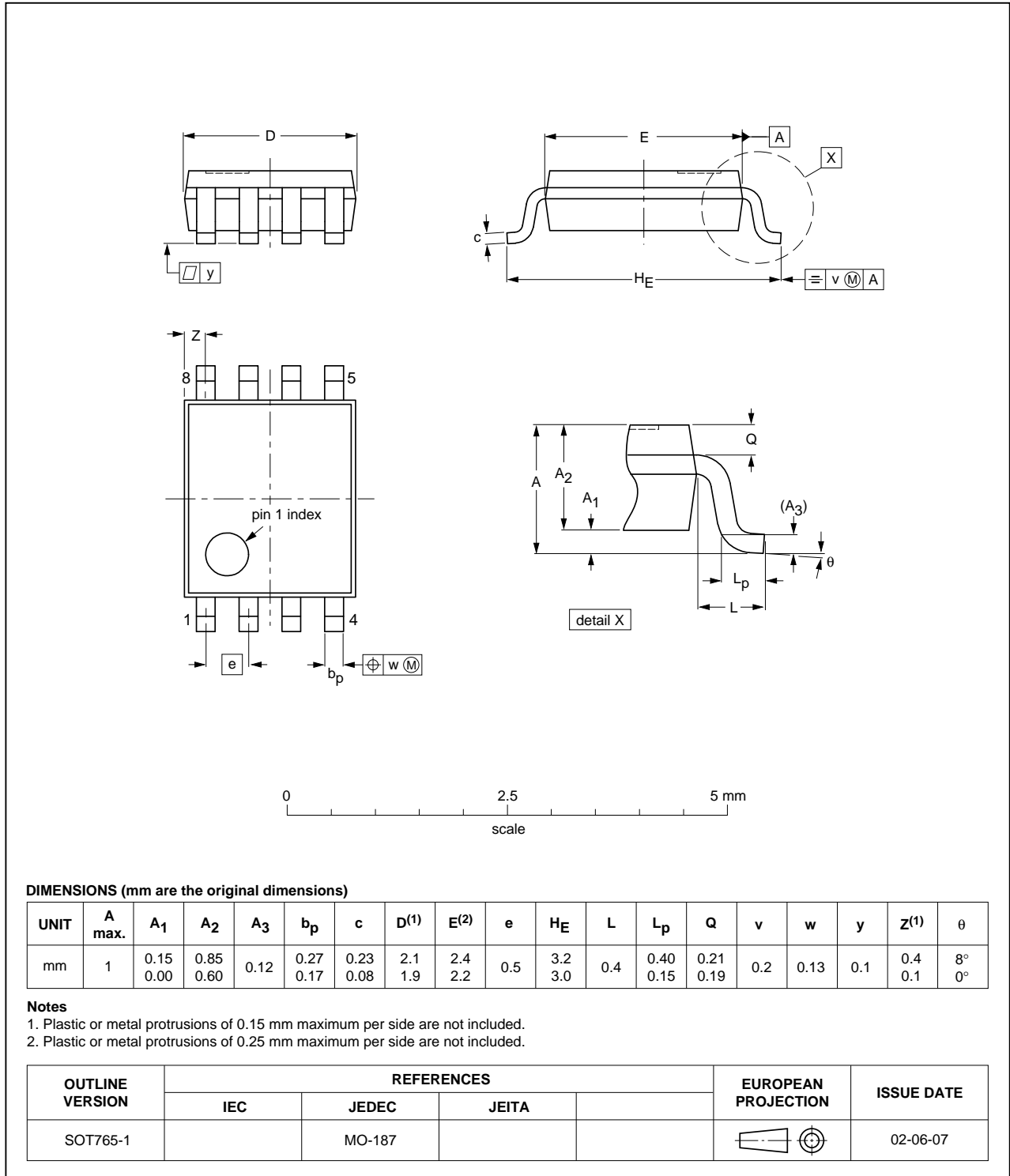


Fig 9. Package outline SOT765-1 (VSSOP8)

XSON8: plastic extremely thin small outline package; no leads;
8 terminals; body 3 x 2 x 0.5 mm

SOT996-2

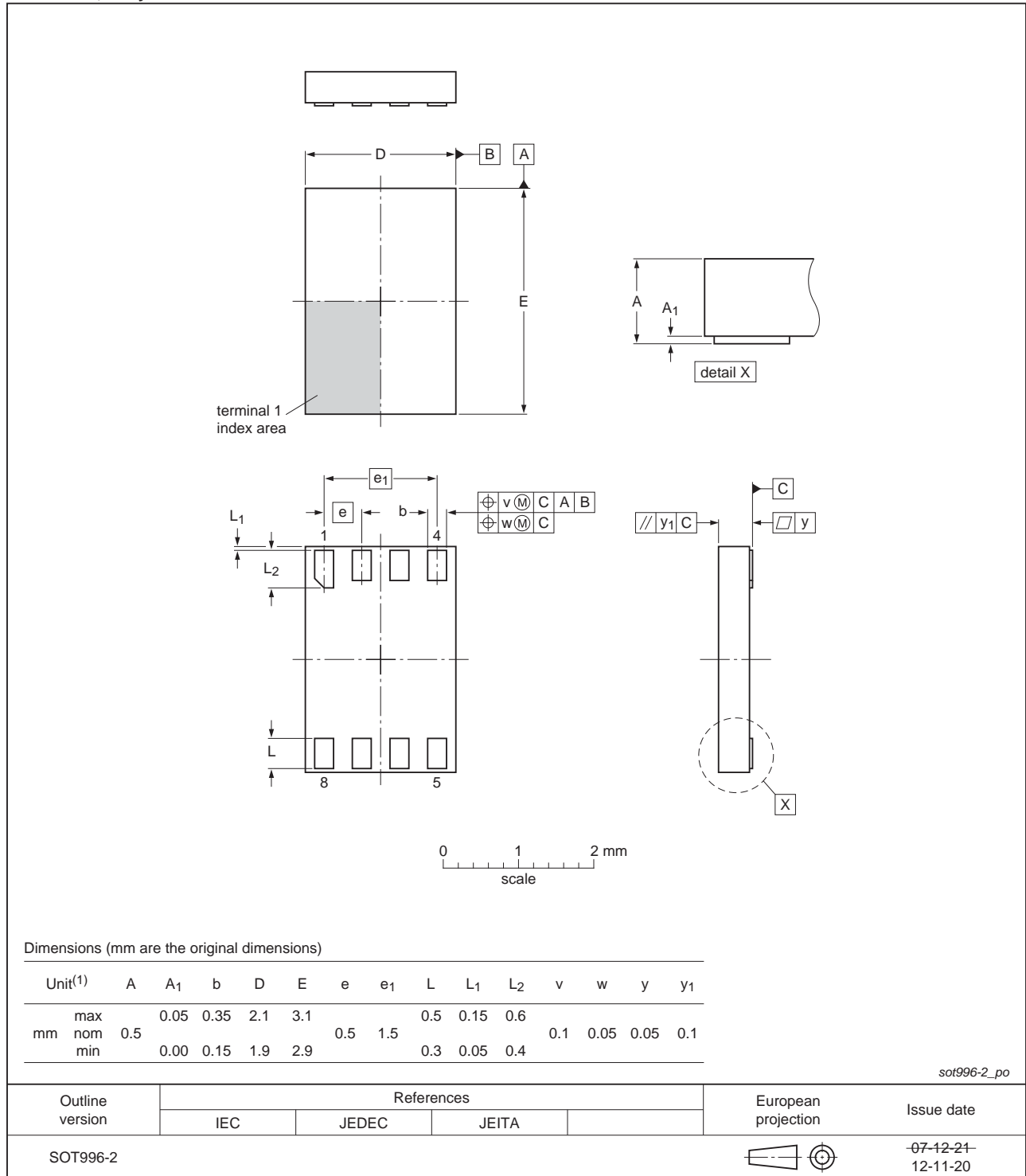


Fig 10. Package outline SOT996-2 (XSON8)

14. Abbreviations

Table 11. Abbreviations

| Acronym | Description |
|---------|---|
| CMOS | Complementary Metal Oxide Semiconductor |
| DUT | Device Under Test |
| ESD | ElectroStatic Discharge |
| HBM | Human Body Model |
| MM | Machine Model |
| TTL | Transistor-Transistor Logic |

15. Revision history

Table 12. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|------------------|--|-----------------------|---------------|------------------|
| 74HC_HCT3G07 v.4 | 20131216 | Product data sheet | - | 74HC_HCT3G07 v.3 |
| Modifications: | <ul style="list-style-type: none"> Features and benefits updated (errata). | | | |
| 74HC_HCT3G07 v.3 | 20130814 | Product data sheet | - | 74HC_HCT3G07 v.2 |
| Modifications: | <ul style="list-style-type: none"> For type numbers 74HC3G07GD and 74HCT3G07GD XSON8U has changed to XSON8. | | | |
| 74HC_HCT3G07 v.2 | 20090512 | Product data sheet | - | 74HC_HCT3G07 v.1 |
| 74HC_HCT3G07 v.1 | 20031015 | Product specification | - | - |

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16.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
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[1] Please consult the most recently issued document before initiating or completing a design.

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18. Contents

| | | |
|------|--|----|
| 1 | General description | 1 |
| 2 | Features and benefits | 1 |
| 3 | Ordering information | 1 |
| 4 | Marking | 2 |
| 5 | Functional diagram | 2 |
| 6 | Pinning information | 2 |
| 6.1 | Pinning | 2 |
| 6.2 | Pin description | 3 |
| 7 | Functional description | 3 |
| 8 | Limiting values | 3 |
| 9 | Recommended operating conditions | 4 |
| 10 | Static characteristics | 4 |
| 11 | Dynamic characteristics | 5 |
| 12 | Waveforms | 6 |
| 13 | Package outline | 8 |
| 14 | Abbreviations | 11 |
| 15 | Revision history | 11 |
| 16 | Legal information | 12 |
| 16.1 | Data sheet status | 12 |
| 16.2 | Definitions | 12 |
| 16.3 | Disclaimers | 12 |
| 16.4 | Trademarks | 13 |
| 17 | Contact information | 13 |
| 18 | Contents | 14 |

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